



FQB2P25 / FQI2P25

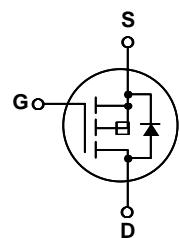
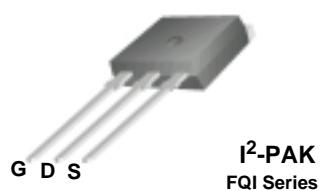
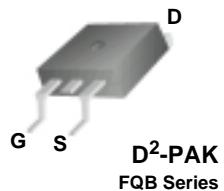
250V P-Channel MOSFET

General Description

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters.

Features

- 2.3A, -250V, $R_{DS(on)} = 4.0\Omega$ @ $V_{GS} = -10\text{ V}$
- Low gate charge (typical 6.5 nC)
- Low C_{rss} (typical 6.5 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQB2P25 / FQI2P25	Units
V_{DSS}	Drain-Source Voltage	-250	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	-2.3	A
	- Continuous ($T_C = 100^\circ\text{C}$)	-1.45	A
I_{DM}	Drain Current - Pulsed	(Note 1)	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	mJ
I_{AR}	Avalanche Current	(Note 1)	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	V/ns
P_D	Power Dissipation ($T_A = 25^\circ\text{C}$) *	3.13	W
	Power Dissipation ($T_C = 25^\circ\text{C}$)	52	W
	- Derate above 25°C	0.42	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	2.4	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	--	40	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	$^\circ\text{C/W}$

* When mounted on the minimum pad size recommended (PCB Mount)

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-250	--	--	V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C	--	-0.2	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = -250 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	--	--	-1	μA
		$V_{\text{DS}} = -200 \text{ V}, T_C = 125^\circ\text{C}$	--	--	-10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = -30 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	--	--	-100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = 30 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	--	--	100	nA
On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250 \mu\text{A}$	-3.0	--	-5.0	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = -10 \text{ V}, I_D = -1.15 \text{ A}$	--	3.15	4.0	Ω
g_{FS}	Forward Transconductance	$V_{\text{DS}} = -40 \text{ V}, I_D = -1.15 \text{ A}$ (Note 4)	--	1.2	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}} = -25 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 1.0 \text{ MHz}$	--	190	250	pF
C_{oss}	Output Capacitance		--	40	55	pF
C_{rss}	Reverse Transfer Capacitance		--	6.5	8.5	pF
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}} = -125 \text{ V}, I_D = -2.3 \text{ A}, R_G = 25 \Omega$	--	8.5	25	ns
t_r	Turn-On Rise Time		--	40	90	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	12	35	ns
t_f	Turn-Off Fall Time		--	25	60	ns
Q_g	Total Gate Charge	$V_{\text{DS}} = -200 \text{ V}, I_D = -2.3 \text{ A}, V_{\text{GS}} = -10 \text{ V}$	--	6.5	8.5	nC
Q_{gs}	Gate-Source Charge		--	1.8	--	nC
Q_{gd}	Gate-Drain Charge		--	3.0	--	μC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	-2.3	--	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	-9.2	--	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}, I_S = -2.3 \text{ A}$	--	--	-5.0	V
t_{rr}	Reverse Recovery Time	$V_{\text{GS}} = 0 \text{ V}, I_S = -2.3 \text{ A}, dI_F / dt = 100 \text{ A}/\mu\text{s}$	--	110	--	ns
Q_{rr}	Reverse Recovery Charge		--	0.4	--	μC

Notes:

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $L = 36\text{mH}$, $I_{AS} = -2.3\text{A}$, $V_{DD} = -50\text{V}$, $R_G = 25 \Omega$. Starting $T_J = 25^\circ\text{C}$
- $I_{SP} \leq -2.3\text{A}$, $d/dt \leq 300\text{A}/\mu\text{s}$, $V_{DD} \leq \text{BV}_{\text{DSS}}$. Starting $T_J = 25^\circ\text{C}$
- Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
- Essentially independent of operating temperature

Typical Characteristics

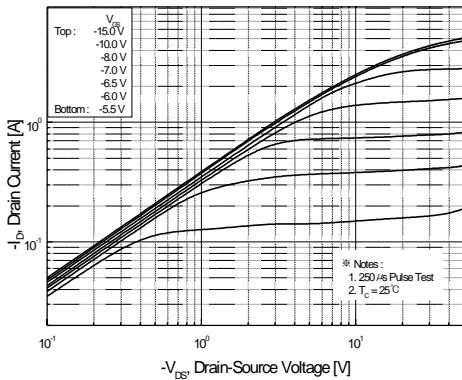


Figure 1. On-Region Characteristics

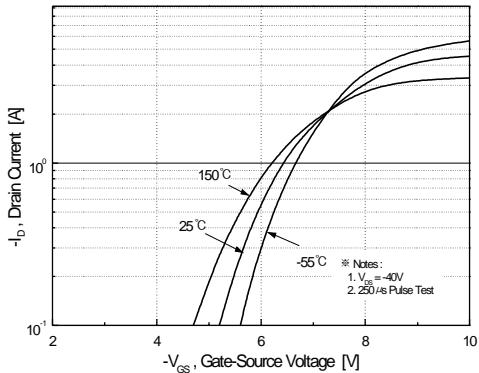


Figure 2. Transfer Characteristics

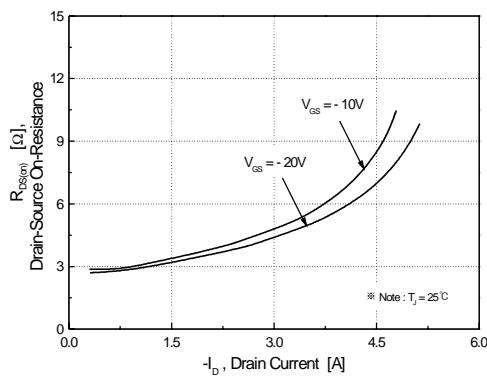


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

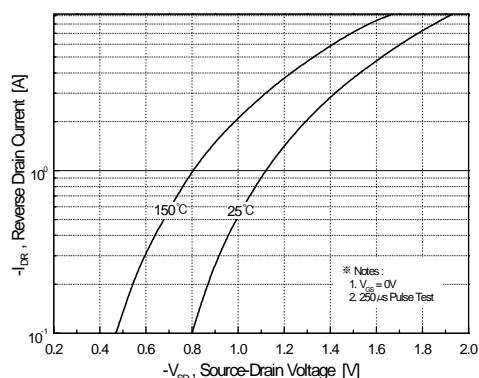


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

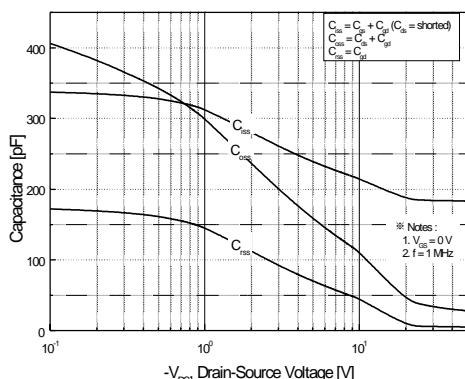


Figure 5. Capacitance Characteristics

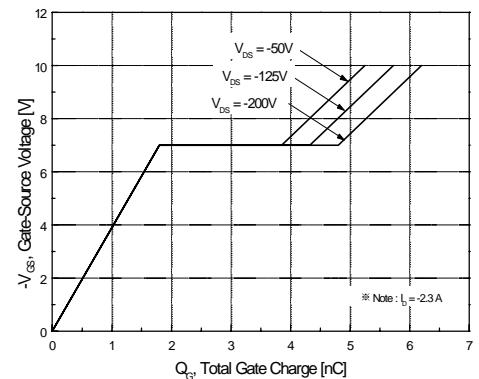


Figure 6. Gate Charge Characteristics